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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/942,626	08/31/2001	Sci Tsunoda	213480US0	8767
22850	7590	01/18/2006	EXAMINER	
OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C. 1940 DUKE STREET ALEXANDRIA, VA 22314			VIJAYAKUMAR, KALLAMBELLA M	
		ART UNIT	PAPER NUMBER	
		1751		

DATE MAILED: 01/18/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

Response to Rule 312 Communication	Application No.	Applicant(s)	
	09/942,626	TSUNODA ET AL.	
	Examiner	Art Unit	
	Kallambella Vijayakumar	1751	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

1. The amendment filed on 07 December 2005 under 37 CFR 1.312 has been considered, and has been:

- a) entered.
- b) entered as directed to matters of form not affecting the scope of the invention.
- c) disapproved because the amendment was filed after the payment of the issue fee.
Any amendment filed after the date the issue fee is paid must be accompanied by a petition under 37 CFR 1.313(c)(1) and the required fee to withdraw the application from issue.
- d) disapproved. See explanation below.
- e) entered in part. See explanation below.

The IDS filed 08/26/2005 is in compliance with the provisions of 37 CFR 1.97 and has been considered along with the references cited therein. The IDS filed 10/28/2005 and 12/07/2005 are the duplicates of the IDS filed on 08/26/2005. The closest prior art cited in the IDS, the US Patent 5,855,962 issued to Cote et al teaches an insulating layer over a substrate formed by coating a mixture of a borazene or its derivative and silsequioxane, wherein the all the terminals of the borazene are connected to Silica (Fig-5). The prior art fails to teach or suggestive of a semiconductor device containing an insulation film containing the applicant's specific borazene moieties disposed between semiconductor layers.

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